

## **APPENDIX C**

### **complete set of "clean" claims pursuant to 37 C.F.R. §1.121(c)(3)**

1. A semiconductor device comprising, in combination, a silicon substrate having a first and second surface; a first layer disposed on said first surface and having impurities of the n or p conductivity type uniformly distributed throughout the volume of said first layer; a second layer disposed on said first layer; said second layer having impurities of the same type as those in said first layer uniformly distributed therethrough and having a substantially uniform resistivity; the concentration of impurities in said second layer being greater than the concentration of impurities in said first layer; and a plurality of diffusions of a conductivity type opposite to that of said second layer distributed uniformly into the surface of said second layer and defining p-n junctions therein; said plurality of diffusions being spaced from one another and each having a depth that is less than the thickness of said second layer whereby each diffusion is wholly contained within said second layer.

2. The device of claim 1 wherein the resistivity of said second layer is lower than that of said first layer.

3. The device of claim 1 wherein the thickness of said first layer is greater than that of said second layer.

4. The device of claim 2 wherein the thickness of said first layer is greater than that of said second layer.

9. The device of claim 8 wherein said device is a vertical conduction power MOSFET.